



Material Content Data Sheet



Halogen-Free

Sales Product Name	IPD50N06S4-09	Issued	13. May 2021
MA#	MA001913412		
Package	PG-TO252-3-11	Weight*	371.07 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.120	0.57	0.57	5713	5713
leadframe	inorganic material	phosphorus	7723-14-0	0.065	0.02		174	
	non noble metal	iron	7439-89-6	0.215	0.06		580	
	non noble metal	copper	7440-50-8	215.017	57.94	58.02	579456	580210
wire	non noble metal	aluminium	7429-90-5	3.080	0.83	0.83	8302	8302
encapsulation	inorganic material	zinc oxide	1314-13-2	1.253	0.34		3378	
	miscellaneous	miscellaneous	-	6.267	1.69		16889	
	plastics	epoxy resin	-	18.801	5.07		50668	
	inorganic material	silicon dioxide	60676-86-0	99.020	26.69	33.79	266853	337788
lead finish	non noble metal	tin	7440-31-5	3.740	1.01	1.01	10079	10079
plating	inorganic material	phosphorus	7723-14-0	0.000			1	
	non noble metal	nickel	7440-02-0	0.091	0.02	0.02	245	246
solder	non noble metal	tin	7440-31-5	0.044	0.01		118	
	noble metal	silver	7440-22-4	0.055	0.01		148	
	non noble metal	lead	7439-92-1	2.095	0.56	0.58	5646	5912
heatspreader	inorganic material	phosphorus	7723-14-0	0.006			16	
	non noble metal	iron	7439-89-6	0.019	0.01		52	
	non noble metal	copper	7440-50-8	19.177	5.17	5.18	51682	51750
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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